

TAPE LIST

Item Name	BG/DC	UV/ Non-UV	Use & Properties	Thickness (μm)	Base Material (μm)	Adhesive	Adhesive Strength (Before UV) mN/25mm	Adhesive Strength (After UV) mN/25mm	Color	Heatproof temperature	Surface Resistivity Ω/□
DX-TAD85C-R-X	DC	UV	Use: Silicon Wafer Properties: Prevents chipping, Supports small chips	85	PVC70	Acrylic15	6500	260	Colorless(Translucent)	60°C few min.	
DX-TAD95C	DC	UV	Use: Silicon Wafer Properties: Transparent, Highly expandable	95	PVC80	Acrylic15	3000	150	Colorless(Transparent)	60°C few min.	
DX-TAD95C-AS	DC	UV	Use: Silicon Wafer Properties: Transparent, Highly expandable RoHS2.0 compliant Antistatic	95	PVC80	Acrylic15	2900	150	Colorless(Transparent)	60°C few min.	10 ¹⁰ ~10 ¹¹
DX-TAU115	DC	UV	Glass, Ceramics	115	PET100	Acrylic15	19000	100	Colorless(Transparent)		
DX-TAU125B	DC	UV	Use: Packaging substrates, hard to cut surfaces Properties: Strong adhesive	125	PET100	Acrylic25	30000	150	Colorless(Transparent)	130°C 30 min.	
DX-TAU213F	DC	UV	Use: Packaging substrates, hard to cut surfaces Properties: Strong adhesive	213	PET188	Acrylic25	40000	170	Colorless(Transparent)	130°C 30 min.	
DX-TAP100	DC	UV	Packaging Substrates, Glass	100	P090	Acrylic10	6300	180	Frosted(Translucent)		
DX-TAP110	DC	UV	Packaging Substrates, Glass	110	P0100	Acrylic10	10000	100	Colorless(Translucent)	40°C few min.	
DX-TAP165EZ	DC	UV	Use: Packaging substrates Properties: Strong adhesive, Prevents chipping	165	P0150	Acrylic15	25000	200	Colorless(Translucent)		
DX-TAP165	DC	UV	Packaging Substrates, Glass	165	P0150	Acrylic15	19000	180	Frosted(Translucent)		
DX-TAP175	DC	UV	Packaging Substrates, Glass	175	P0150	Acrylic25	20000	200	Frosted(Translucent)		
DX-TAP200	DC	UV	Packaging Substrates, Glass	200	P0150	Acrylic50	23000	200	Frosted(Translucent)		
DX-TAB165C	DC	UV	Use: Packaging substrates Properties: Prevents chipping, Easily peeled by hand	165	EVA150	Acrylic15	15000	140	Colorless(Transparent)	40°C few min.	
DX-LCP180K	BG	UV	BG standard compatible Properties: High tape thickness accuracy, easy to peel even for thin film products thanks to UV peeling process	180	P0150	Urethane30	18000	100	Colorless(Transparent)	40°C few min.	
DX-LCP130GX	BG	UV	BG standard compatible Properties: Reasonably high tape thickness accuracy, relatively easy to peel even for thin film products thanks to UV peeling process	130	P0100	Urethane30	13500	90	Colorless(Translucent)	40°C few min.	
DX-LCP130GNX	BG	Non-UV	BG standard compatible Properties: General purpose use	130	P0100	Acrylic30	1200	—	Blue(transparent)	40°C few min.	
DX-LCP180LNX	BG	Non-UV	BG standard compatible Properties: High tape thickness accuracy, Increased adhesive strength	180	P0150	Acrylic30	1400	—	Blue(transparent)	40°C few min.	
DX-LCP200LNX	BG	Non-UV	BG standard compatible Properties: High tape thickness accuracy, Increased adhesive strength	200	P0150	Acrylic50	1900	—	Blue(transparent)	40°C few min.	
DX-LCP290Z	BG	UV	Supports Bump Wafers	290	P0150	Acrylic140	22000	190	Colorless(Transparent)		

The products and specifications described in the catalog may be changed or discontinued without prior notice for improvement.



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